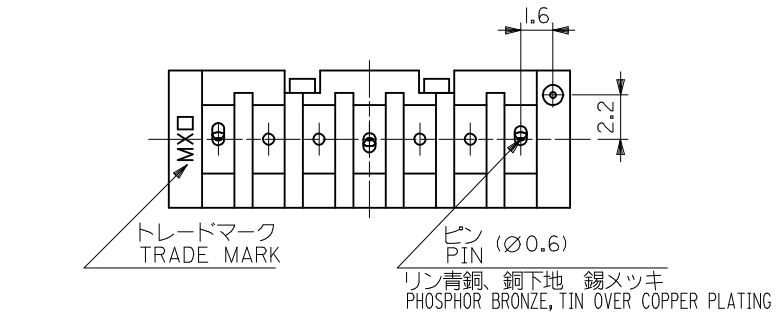
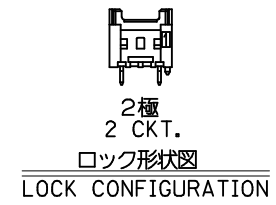
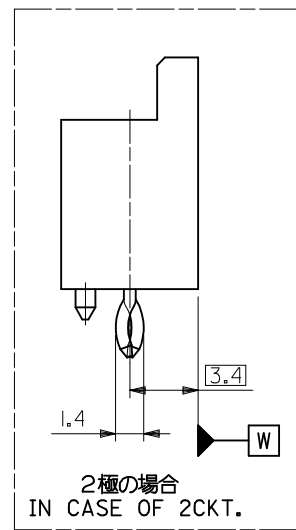
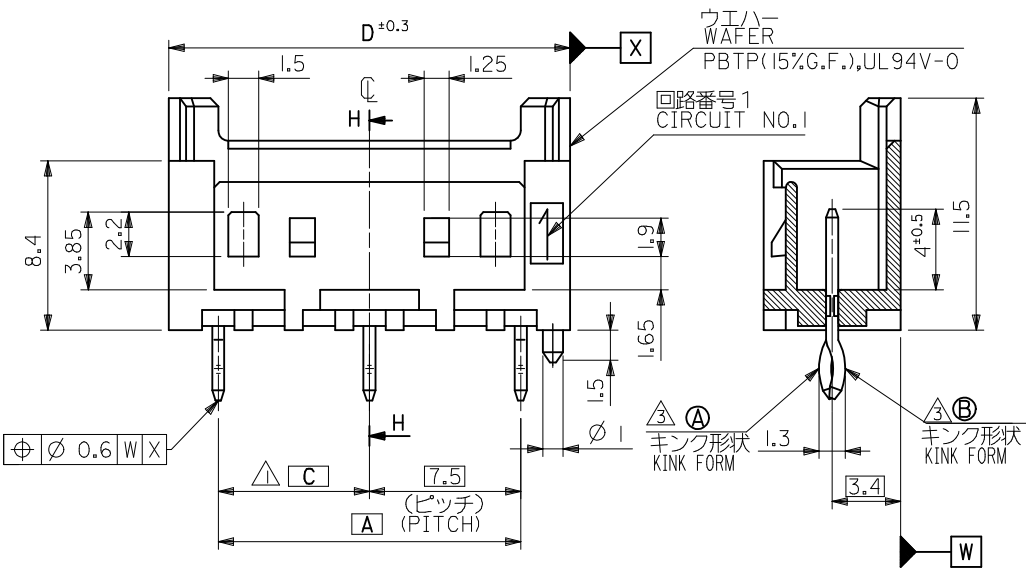


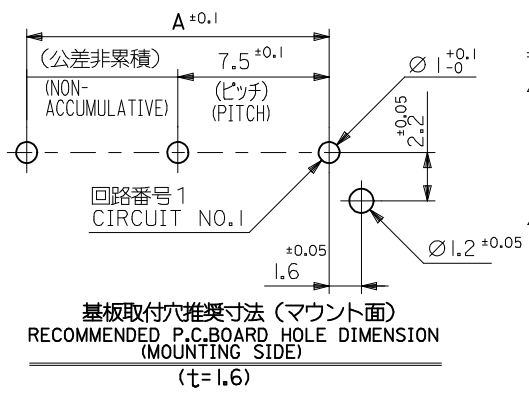
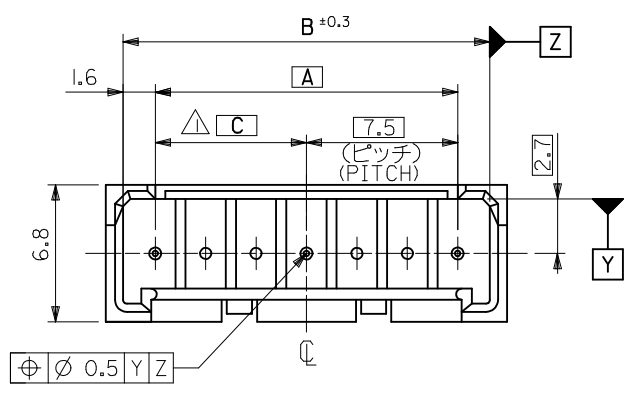
注記 NOTES

- △ ウエハの \varnothing から隣接するピンの \varnothing までの位置を示す。
SHOW POSITION FROM \varnothing OF WAFER TO \varnothing OF ADJACENT PIN.
- 2. 嵌合相手: 51102, 51103 シリーズ
MATES WITH: 51102, 51103 SERIES.
- △ 3極以上のキンク形状は両サイドが (A)、その他の極はすべて (B) 形状とする。
KINK FORM MORE THAN 2 CURCUIT:
PINS AT BOTH ENDS ARE KINK FORMED TO (A), THE OTHER PINS ARE KINK FORMED TO (B).



RED	19.9	7.5	18.2	15	53388-0312	3
	34.9	7.5	33.2	30	53388-0510	5
NATURAL	27.4	3.75	25.7	22.5	53388-0410	4
	19.9	7.5	18.2	15	53388-0310	3
COLOR	D	C	B	A	MATERIAL NO.	極数 NO. OF CKTS.

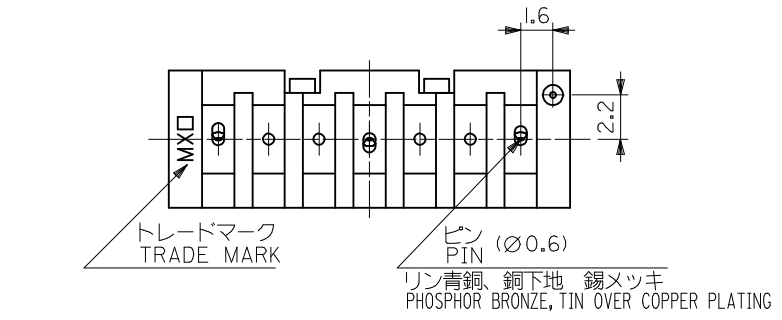
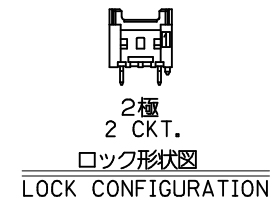
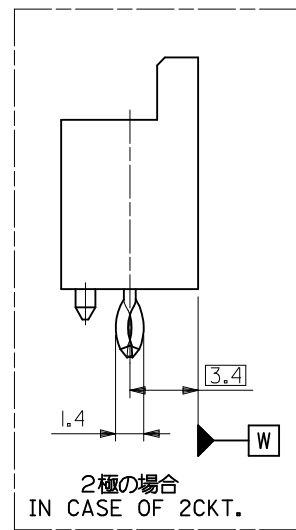
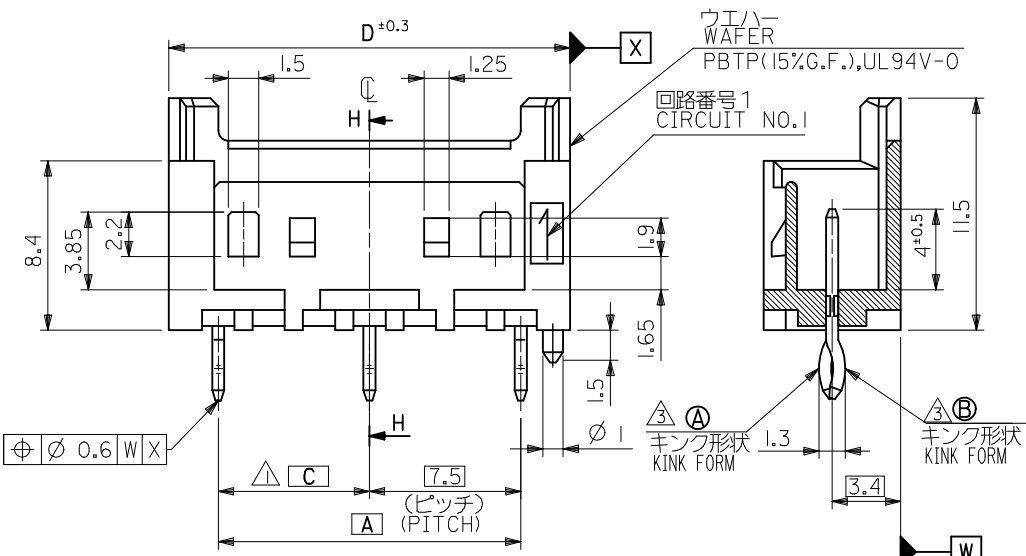
REVISED EC NO: J2017-0525 DRWN: SAT002 CHK: DAIDA APPR: KANEKO 2017/04/13 2017/04/13 2017/04/14	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE 4.0	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION
	0.25 UNDER	UNDER	±	DRAWN BY K. TOJO	DATE 1992/12/22	TITLE 7.5 WIRE TO BOARD CONN. WAFER ASSY -LEAD FREE-	
	0.25 OVER	0.5 UNDER	±	CHECKED BY H. HIRAMOTO	DATE 1993/07/16		
	0.5 OVER	1.0 UNDER	±	APPROVED BY	DATE		
	1.0 OVER	10 UNDER	± 0.2	MATERIAL NO.		DOCUMENT NO.	SHEET NO.
10 OVER	30 UNDER	± 0.25	SEE CHART		SD-53388-**10	1 OF 1	
30 OVER		± 0.3	SIZE A3		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX ELECTRONIC TECHNOLOGIES, LLC AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION		
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS							



注記
NOTES

- △ ウエハの ϕ から隣接するピンの ϕ までの位置を示す。
SHOW POSITION FROM ϕ OF WAFER TO ϕ OF ADJACENT PIN.
- 2. 嵌合相手：51102,51103 シリーズ
MATES WITH：51102,51103 SERIES.
- △ 3極以上のキンク形状は両サイドが (A)、その他の極はすべて (B) 形状とする。
KINK FORM MORE THAN 2 CURCUIT:
PINS AT BOTH ENDS ARE KINK FORMED TO (A), THE OTHER PINS ARE KINK FORMED TO (B).

基板取付穴推奨寸法 (マウント面)
RECOMMENDED P.C.BOARD HOLE DIMENSION (MOUNTING SIDE)
($t=1.6$)



断面 H-H
SECT. H-H

RED	19.9	7.5	18.2	15	53388-0312	3
NATURAL	34.9	7.5	33.2	30	53388-0510	5
	27.4	3.75	25.7	22.5	53388-0410	4
	19.9	7.5	18.2	15	53388-0310	3
COLOR	D	C	B	A	MATERIAL NO.	極数 No. of CKTS.

REVISED EC NO: J2017-0525 DRWN: SAT002 CHKD: AIDA APPR: KANEKO 2017/04/13 2017/04/13 2017/04/14	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE 4.0	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION
	0.25 UNDER	UNDER	±	DRAWN BY K. TOJO	DATE 1992/12/22	TITLE 7.5 WIRE TO BOARD CONN. WAFER ASSY -LEAD FREE-	
	0.25 OVER	0.5 UNDER	±	CHECKED BY H. HIRAMOTO	DATE 1993/07/16		
	0.5 OVER	1.0 UNDER	±	APPROVED BY	DATE		
	1.0 OVER	10 UNDER	±0.2	MATERIAL NO.		DOCUMENT NO.	SHEET NO.
10 OVER	30 UNDER	±0.25	SEE CHART		SD-53388-**10	1 OF 1	
30 OVER		±0.3	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX ELECTRONIC TECHNOLOGIES, LLC AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION				
ANGULAR		±3 °	SIZE A3				
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS							